

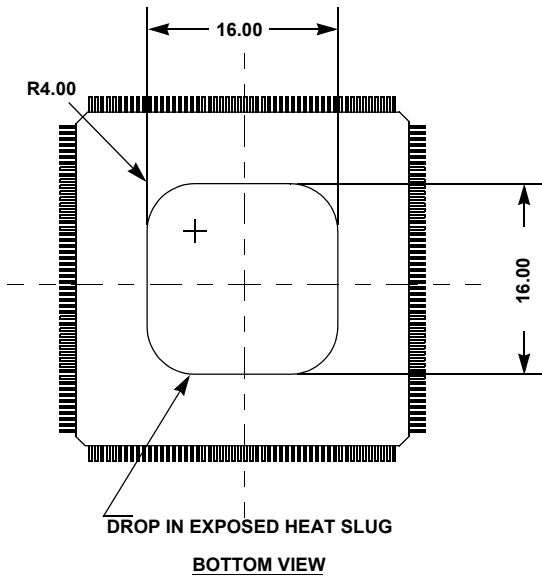
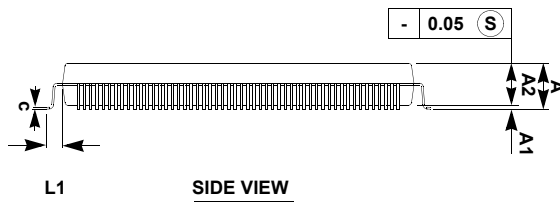
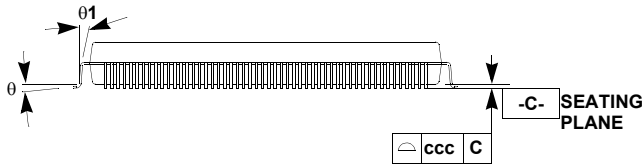
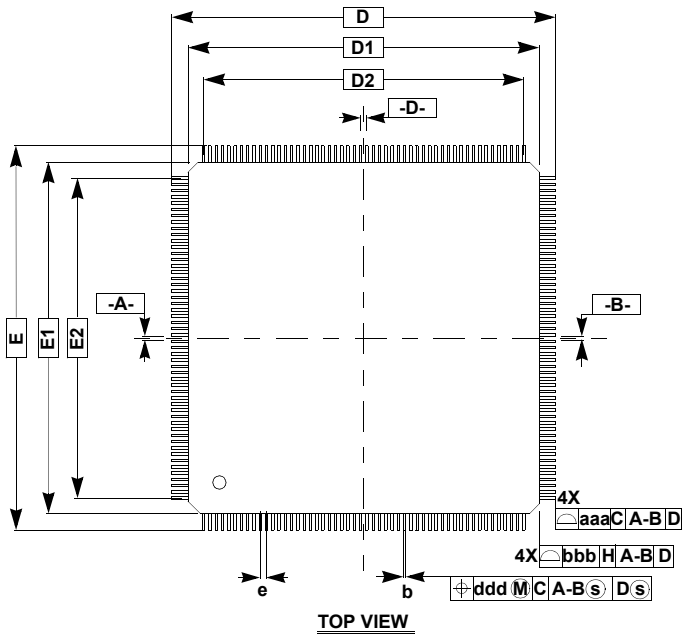
Plastic Packages for Integrated Circuits

Package Outline Drawing

Q208.28x28E

208 LEAD PLASTIC QUAD FLATPACK PACKAGE WITH EXPOSED PAD (PQFP-EP)

Rev 1, 6/13



SYMBOL	MILLIMETERS			INCHES		
	MIN	NOM	MAX	MIN	NOM	MAX
A	-	-	4.10	-	-	0.161
A1	0.25	-	-	0.010	-	-
A2	3.20	3.32	3.60	0.126	0.131	0.142
D	30.60 BSC			1.205 BSC		
D1	28.00 BSC			1.102 BSC		
E	30.60 BSC			1.205 BSC		
E1	28.00 BSC			1.102 BSC		
R2	0.08	-	0.25	0.003	-	0.010
R1	0.08	-	-	0.003	-	-
q	0°	3.5°	7°	0°	3.5°	7°
q1	0°	-	-	0°	-	-
q2	8° REF			8° REF		
q3	8° REF			8° REF		
c	0.09	0.15	0.20	0.004	0.006	0.008
L	0.45	0.60	0.75	0.018	0.024	0.030
L1	1.30 REF			0.051 REF		
S	0.20	-	-	0.008	-	-
b	0.17	0.20	0.27	0.007	0.008	0.011
e	0.50 BSC			0.020 BSC		
D2	25.50			1.004		
E2	25.50			1.004		
TOLERANCES OF FORM AND POSITION						
aaa	0.20			0.008		
bbb	0.20			0.008		
ccc	-	0.08	-	-	0.003	-
ddd	-	0.08	-	-	0.003	-

NOTES:

1. Dimensions D1 and E1 do not include mold protrusion.
2. Dimension b does not include dambar protrusion. Allowable dambar protrusion shall not cause the lead width to exceed the maximum b dimension by more than 0.08mm. Dambar cannot be located on the lower radius or the foot. Minimum space between protrusion and an adjacent lead shall not be less than 0.07mm.
3. The top package body size may be smaller than the bottom package body size.
4. JEDEC Spec MS-0-029.

